

Power Modules: Variants Explanation



FORMS-1014 / Rev. 06

Content

1. General Information

2. MiniSKiiP® Lid Options

3. Thermal Interface Materials

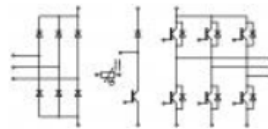
FORMS-1014 / Rev. 06

Variants Explanation: General Information

Online Shop Variants:

Customers can choose from a range of product variants regarding:

- Pressure lid type for MiniSKiiP® modules: standard or slim lids
- Thermal interface materials: thermal paste or phase change material



SKiiP 11NAB12T4V1

MiniSKiiP® 1

V_{CES} 1200 V
I_{cnom} 8 A

Part Number: 25231580
Net unit weight: 0.03 kg
Tariff Number: 85412900
Country of Origin: Germany
Manufacturer: SEMIKRON

[datasheet](#)

EUR | USD

Choose variant ▼

std. lid (6.5mm)

slim lid (2.8mm)

std. lid (6.5mm), therm.paste

slim lid (2.8mm), therm.paste

no accessories

with therm.paste only

Code	VARIANT DESCRIPTION	M10	With Slim Lid (2.8 mm)
M00	Power Module only	M11	With Slim Lid and Thermal Paste P12
M01	With Thermal Paste P12	M20	With Standard Lid (6.5 mm)
M04	With Phase Change Material HALA P8	M21	With Standard Lid and Thermal Paste P12

FORMS-1014 / Rev. 06

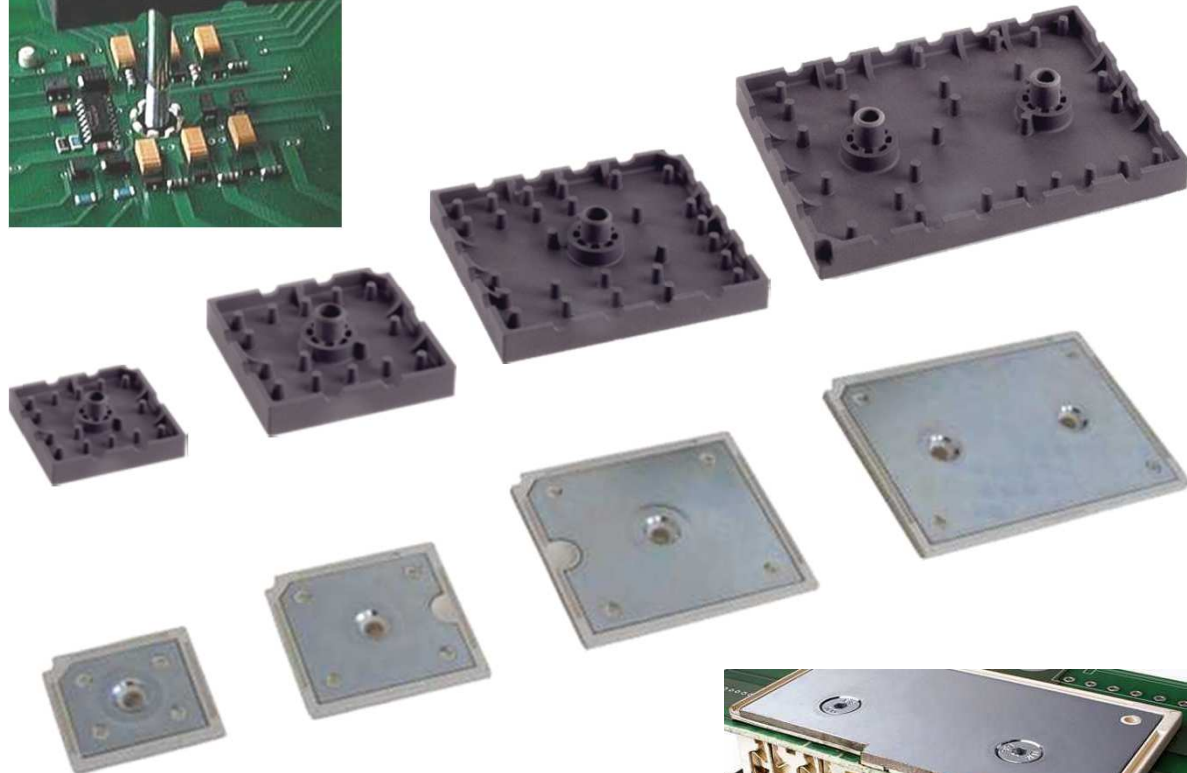
MiniSKiiP® Variants Explanation: Lid Options

- Standard Lid:

Lid height of 6.5 mm.
Ample space for SMD components (max. height 3.5 mm)



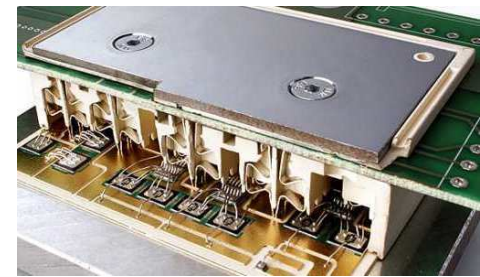
Standard Lid 6.5 mm



- Slim Lid:

Lid height of 2.8 mm.
Slim solution for minimum height requirement

Slim Lid 2.8 mm



Variants Explanation: Thermal Interface Materials

- With Thermal Paste (P12):

For a fast and easy assembly of the module on the heat sink with an optimum thickness of thermal paste layer.

- With Phase Change Material (HALA P8):

PCM with excellent conductive property which is applied in a fluid state, it is solid at room temperature and is silicone free.

